# Final Product/Process Change Notification

Document #: FPCN23483ZF
Issue Date: 13 Dec 2022

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|---|---|
| **Title of Change:** | Transfer of Assembly and Test operations of SMC products to subcontractor Good-Ark China. |
| **Proposed Changed Material First Ship Date:** | 02 Nov 2023 or earlier if approved by customer |
| **Current Material Last Order Date:** | 01 May 2023<br>*Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability*. |
| **Current Material Last Delivery Date:** | 01 Nov 2023<br>*The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory* |
| **Product Category:** | Active components – Discrete components |
| **Contact information:** | Contact your local onsemi Sales Office or Hoang.Nguyen@onsemi.com |
| **PCN Samples Contact:** | Contact your local onsemi Sales Office to place sample order.<br>Sample requests are to be submitted no later than 45 days after publication of this change notification.<br>Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. |
| **Sample Availability Date:** | 01 Dec 2022 |
| **PPAP Availability Date:** | 01 Dec 2022 |
| **Additional Reliability Data:** | Contact your local onsemi Sales Office or MohdAzizi.Azman@onsemi.com |
| **Type of Notification:** | This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements.<br>onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com. |

**Change Category**

| **Category** | **Type of Change** |
|---|---|
| Test Flow | Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor |
| Equipment | Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product,<br>Change in final test equipment type that uses a different technology |
| Process - Assembly | Move of all or part of assembly to a different location/site/subcontractor.,<br>Change of mold compound,<br>Die attach material |

**Description and Purpose:**

This Final Product Change Notification (FPCN) is to announce the planned qualification to transfer Assembly and Test of SMC products from onsemi Vietnam to subcontractor GoodArk China.

The suffix '-GA01' will be added to the end of the part number.

The products in SMC package are currently being assembled and tested at onsemi Vietnam.

Upon expiration of this FPCN, these products can be processed at Good-Ark location under new part numbers using its Bill of Materials.

| | From | To |
|---|---|---|
| **Assembly Site** | onsemi Vietnam | Good-Ark China |
| **Solder Paste** | SN5AG2.5PB92.5 Indium SMQ75 | SN5AG2.5PB92.5 Indium 9.15 |
| **Mold compound** | NITTO GE-200HH | HYSOL GR530 |

| | From | To |
|---|---|---|
| **Final Test Site** | onsemi Vietnam | Good-Ark China |

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|---|---|
| **Reason / Motivation for Change:** | Supply disruption |
| **Anticipated impact on fit, form, function, reliability, product safety or manufacturability:** | The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded.<br><br>No anticipated impacts. |

**Sites Affected:**

| **onsemi Sites** | **External Foundry/Subcon Sites** |
|---|---|
| None | Good-Ark, China |

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| **Marking of Parts/ Traceability of Change:** | Products from Good-ark will be marked with site code “g” prior to date code. |

**Reliability Data Summary:**

**QV DEVICE NAME : SURS8360T3G-VF01**
**RMS: 83558**
**PACKAGE: SMC**

| Test | Specification | Condition | Interval | Results |
|---|---|---|---|---|
| HTRB | JESD22-A108 | Ta=150°C, 100% max rated V | 1008 hrs | 0/231 |
| HTSL | JESD22-A103 | Ta=150°C | 1008 hrs | 0/231 |
| LTSL | JESD22-A119 | Ta=-40°C | 168 hrs | 0/75 |
| IOL | MIL-STD-750 (M1037) AEC-Q101 | Ta=+25°C, delta Tj=100°C On/off = 2 min | 15000 cyc | 0/231 |
| TC | JESD22-A104 | Ta= -55°C to +150°C, mounted on board | 1000 cyc | 0/231 |
| H3TRB | JESD22-A101 | 85°C, 85% RH, reverse bias | 1008 hrs | 0/231 |
| uHAST | JESD22-A118 | 130°C, 85% RH, 18.8psig, unbiased | 96 hrs | 0/231 |
| PC | J-STD-020 JESD-A113 | MSL 1 @ 260°C | | 0/924 |
| RSH | JESD22- B106 | Ta = 265C, 10 sec | | 0/90 |
| SD | JSTD002 | Ta = 245C, 5 sec | | 0/45 |

**Note: AEC-1pager is attached.**

*To view attachments:*
*1. Download pdf copy of the PCN to your computer*
*2. Open the downloaded pdf copy of the PCN*
*3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field*
*4. Then click on the attached file.*

**Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

**List of Affected Parts:**

***Note:*** *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

| Current Part Number | New Part Number | Qualification Vehicle |
|---|---|---|
| SURS8360T3G-VF01 | SURS8360T3G-GA01 | SURS8360T3G-VF01 |
| SURS8340T3G | SURS8340T3G-GA01 | SURS8360T3G-VF01 |
| SURS8320T3G-VF01 | SURS8320T3G-GA01 | SURS8360T3G-VF01 |